2SK2383

Silicon N-Channel Power F-MOS FET

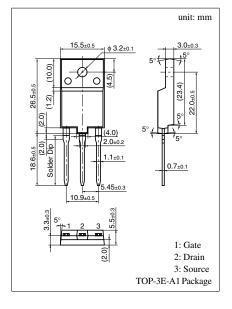
- Features
- Avalanche energy capacity guaranteed
- High-speed switching
- Low ON-resistance
- No secondary breakdown

■ Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

■ Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	500	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I_D	±13		
	Pulse	I_{DP}	±26	A	
Avalanche energy capacity		EAS*	170	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	100	W	
dissipation	Ta = 25°C	$P_{\rm D}$	3		
Channel temperature		T _{ch}	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	

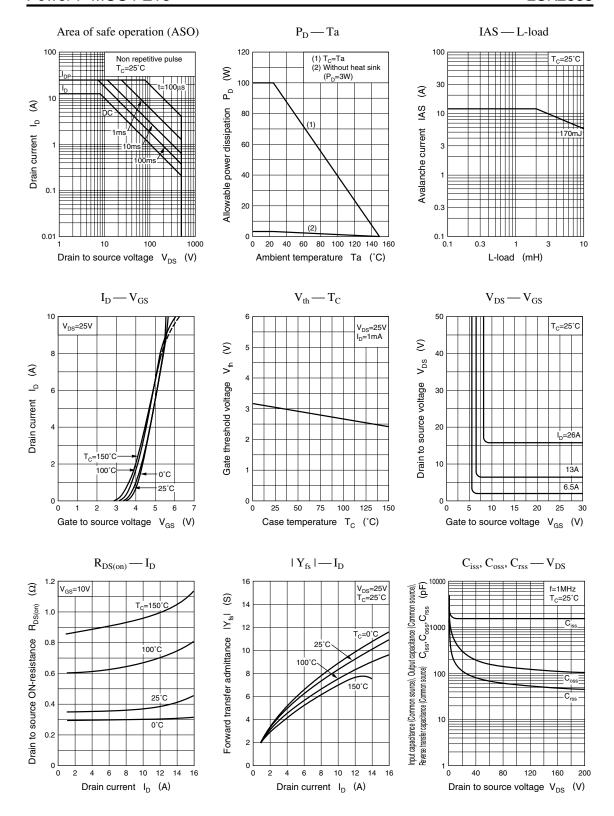


■ Electrical Characteristics $(T_C = 25^{\circ}C)$

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 400V, V_{GS} = 0$			100	μΑ
Gate to Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0$			±1	μΑ
Drain to Source breakdown voltage	V _{DSS}	$I_D = 1$ mA, $V_{GS} = 0$	500			V
Gate threshold voltage	V _{th}	$V_{DS} = 25V, I_D = 1mA$	1		5	V
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 7A$		0.45	0.6	Ω
Forward transfer admittance	Y _{fs}	$V_{DS} = 25V, I_D = 7A$	5	8		S
Diode forward voltage	V _{DSF}	$I_{DR} = 13A, V_{GS} = 0$			-1.7	V
Input capacitance (Common Source)	C _{iss}			1700		pF
Output capacitance (Common Source)	C _{oss}	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		300		pF
Reverse transfer capacitance (Common Source)	C _{rss}			120		pF
Turn-on time (delay time)	t _{d(on)}			30		ns
Rise time	t _r	$V_{DD} = 150V, I_D = 7A$		70		ns
Fall time	$t_{\rm f}$	$V_{GS} = 10V, R_L = 21.4\Omega$		90		ns
Turn-off time (delay time)	t _{d(off)}			210		ns
Thermal resistance between channel and case	R _{th(ch-c)}				1.25	°C/W
Thermal resistance between channel and atmosphere	R _{th(ch-a)}				41.67	°C/W

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^{*} L = 2mH, $I_L = 13A$, 1 pulse



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